

# MJD340 (NPN), MJD350 (PNP)

## High Voltage Power Transistors

### DPAK for Surface Mount Applications

Designed for line operated audio output amplifier, switchmode power supply drivers and other switching applications.

#### Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular MJE340 and MJE350
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	$V_{CEO}$	300	Vdc
Collector-Base Voltage	$V_{CB}$	300	Vdc
Emitter-Base Voltage	$V_{EB}$	3	Vdc
Collector Current – Continuous	$I_C$	0.5	Adc
Collector Current – Peak	$I_{CM}$	0.75	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	15 0.12	W W/ $^\circ\text{C}$
Total Power Dissipation (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.56 0.012	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$
ESD – Human Body Model MJD340 (NPN) MJD350 (PNP)	HBM	3B 2	V
ESD – Machine Model MJD340 (NPN) MJD350 (PNP)	MM	M4 M4	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

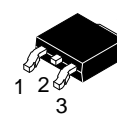
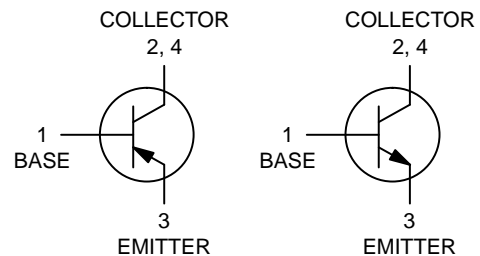
1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



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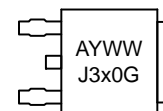
[www.onsemi.com](http://www.onsemi.com)

### SILICON POWER TRANSISTORS 0.5 AMPERE 300 VOLTS, 15 WATTS



DPAK  
CASE 369C  
STYLE 1

#### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
J3x0 = Device Code  
x = 4 or 5  
G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

## MJD340 (NPN), MJD350 (PNP)

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	8.33	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	$^{\circ}\text{C}/\text{W}$
Leading Temperature for Soldering Purpose	$T_L$	260	$^{\circ}\text{C}$

2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

### ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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#### OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage (Note 3) ( $I_C = 1\text{ mA}$ , $I_B = 0$ )	$V_{CEO(sus)}$	300	-	V
Collector Cutoff Current ( $V_{CB} = 300\text{ V}$ , $I_E = 0$ )	$I_{CEO}$	-	0.1	mA
Emitter Cutoff Current ( $V_{BE} = 3\text{ V}$ , $I_C = 0$ )	$I_{EBO}$	-	0.1	mA

#### ON CHARACTERISTICS (Note 3)

DC Current Gain ( $I_C = 50\text{ mA}$ , $V_{CE} = 10\text{ V}$ )	$h_{FE}$	30	240	-
Collector-Emitter Saturation Voltage ( $I_C = 100\text{ mA}$ , $I_B = 10\text{ mA}$ )	$V_{CE(sat)}$	-	1	V
Base-Emitter On Voltage ( $I_C = 1\text{ A}$ , $V_{CE} = 10\text{ V}$ )	$V_{BE(on)}$	-	1.5	V

#### DYNAMIC CHARACTERISTICS

Current Gain – Bandwidth Product ( $I_C = 50\text{ mA}$ , $V_{CE} = 10\text{ V}$ , $f = 10\text{ MHz}$ )	$f_T$	10	-	MHz
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Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

# MJD340 (NPN), MJD350 (PNP)

## TYPICAL CHARACTERISTICS

### MJD340

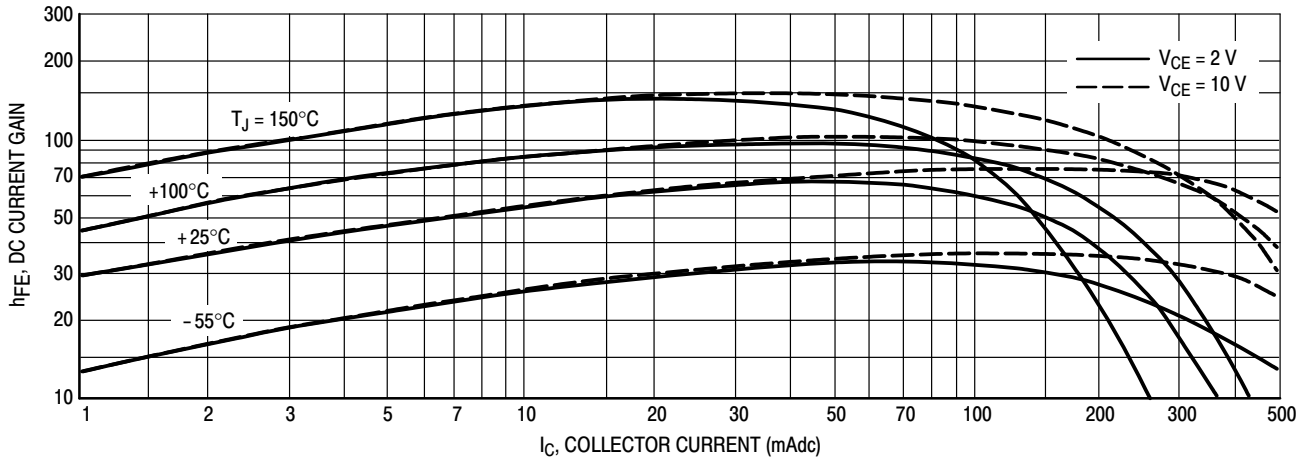


Figure 1. DC Current Gain

### MJD340

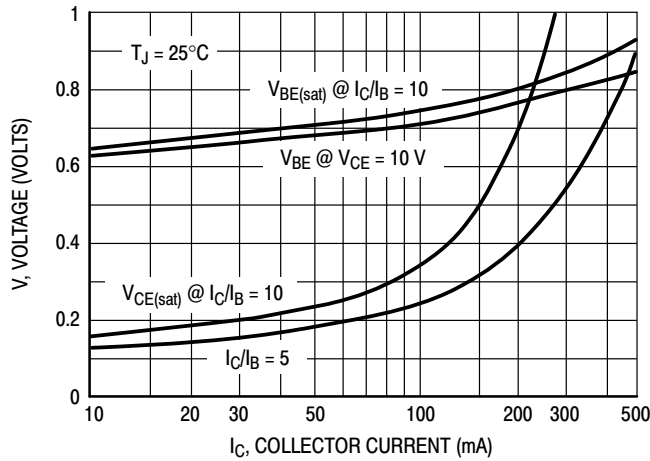


Figure 2. "On" Voltages

### MJD350

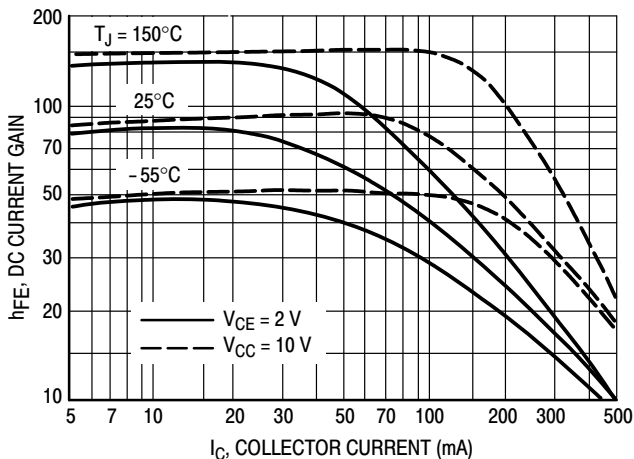


Figure 3. DC Current Gain

### MJD350

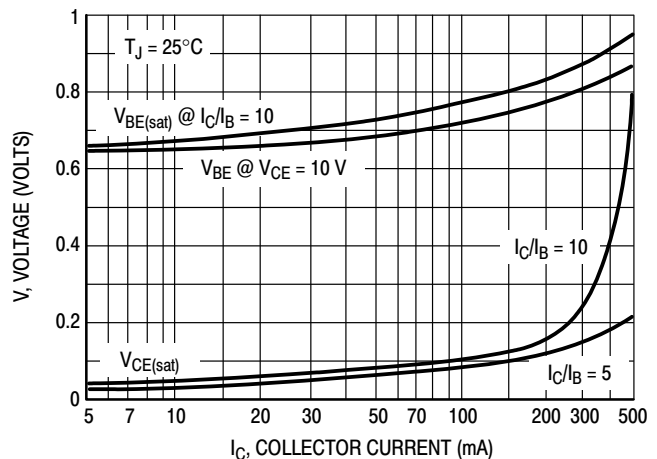


Figure 4. "On" Voltages

# MJD340 (NPN), MJD350 (PNP)

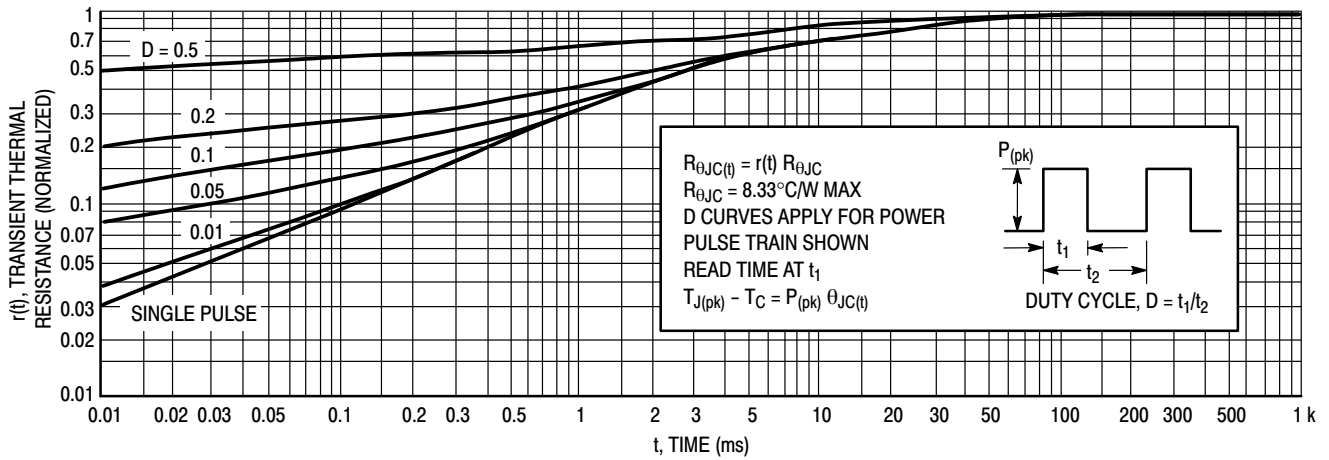


Figure 5. Thermal Response

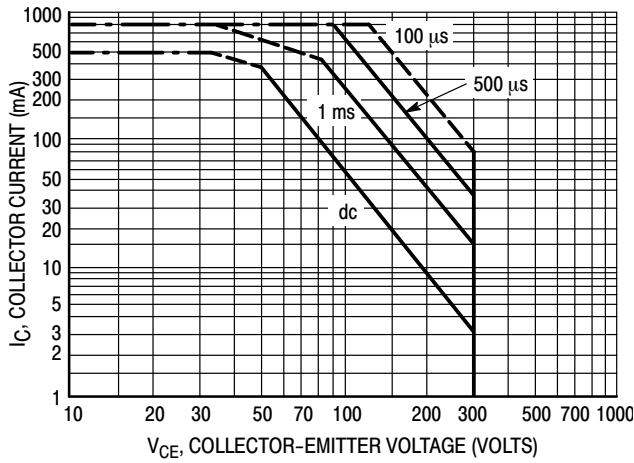


Figure 6. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on  $T_{J(pk)} = 150^{\circ}\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \leq 150^{\circ}\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

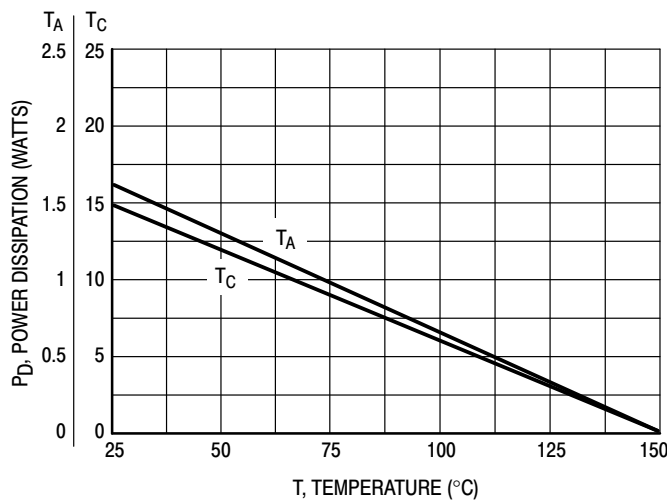


Figure 7. Power Derating

## MJD340 (NPN), MJD350 (PNP)

### ORDERING INFORMATION

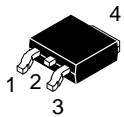
Device	Package	Shipping†
MJD340G	DPAK (Pb-Free)	75 Units / Rail
MJD340RLG	DPAK (Pb-Free)	1,800 / Tape & Reel
MJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
MJD350G	DPAK (Pb-Free)	75 Units / Rail
MJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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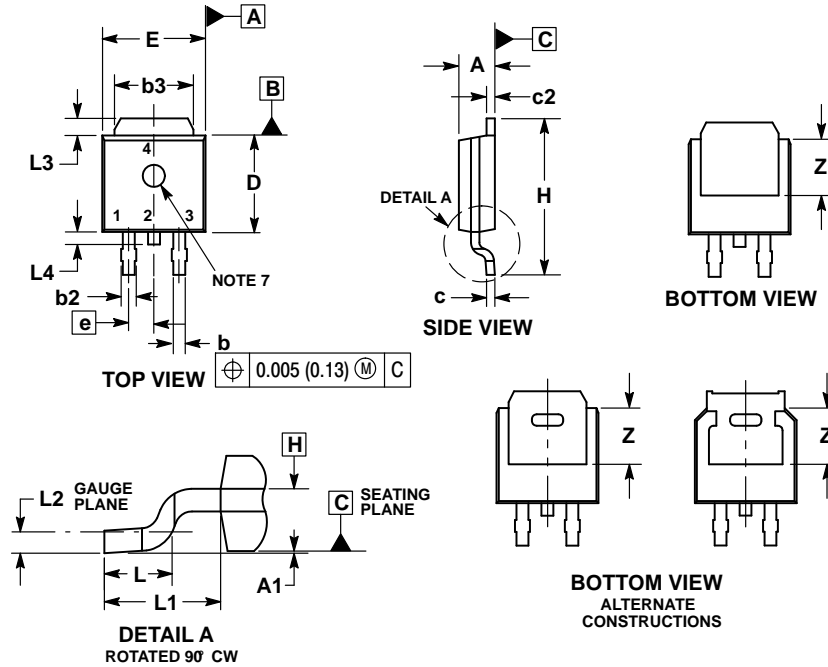
SCALE 1:1

### DPAK (SINGLE GAUGE)

#### CASE 369C

#### ISSUE F

DATE 21 JUL 2015

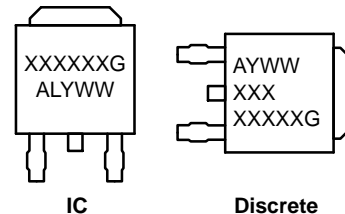


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

### GENERIC MARKING DIAGRAM\*

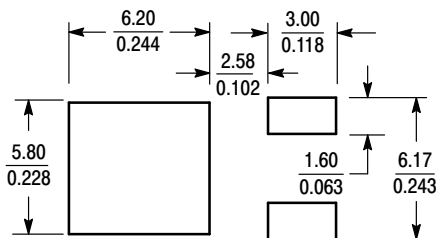


- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

- |  |  |   |   |  |
|--|--|---|---|--|
| <p>STYLE 1:<br/>PIN 1. BASE<br/>2. COLLECTOR<br/>3. EMITTER<br/>4. COLLECTOR</p> | <p>STYLE 2:<br/>PIN 1. GATE<br/>2. DRAIN<br/>3. SOURCE<br/>4. DRAIN</p>          | <p>STYLE 3:<br/>PIN 1. ANODE<br/>2. CATHODE<br/>3. ANODE<br/>4. CATHODE</p> | <p>STYLE 4:<br/>PIN 1. CATHODE<br/>2. ANODE<br/>3. GATE<br/>4. ANODE</p>              | <p>STYLE 5:<br/>PIN 1. GATE<br/>2. ANODE<br/>3. CATHODE<br/>4. ANODE</p>     |
| <p>STYLE 6:<br/>PIN 1. MT1<br/>2. MT2<br/>3. GATE<br/>4. MT2</p>                 | <p>STYLE 7:<br/>PIN 1. GATE<br/>2. COLLECTOR<br/>3. EMITTER<br/>4. COLLECTOR</p> | <p>STYLE 8:<br/>PIN 1. N/C<br/>2. CATHODE<br/>3. ANODE<br/>4. CATHODE</p>   | <p>STYLE 9:<br/>PIN 1. ANODE<br/>2. CATHODE<br/>3. RESISTOR ADJUST<br/>4. CATHODE</p> | <p>STYLE 10:<br/>PIN 1. CATHODE<br/>2. ANODE<br/>3. CATHODE<br/>4. ANODE</p> |

### SOLDERING FOOTPRINT\*




SCALE 3:1 (mm / inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>NEW STANDARD:</b>	<b>REF TO JEDEC TO-252</b>	
<b>DESCRIPTION:</b>	<b>DPAK SINGLE GAUGE SURFACE MOUNT</b>	<b>PAGE 1 OF 2</b>



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY L. GAN	24 SEP 2001
A	ADDED STYLE 8. REQ. BY S. ALLEN.	06 AUG 2008
B	ADDED STYLE 9. REQ. BY D. WARNER.	16 JAN 2009
C	ADDED STYLE 10. REQ. BY S. ALLEN.	09 JUN 2009
D	RELABELLED DRAWING TO JEDEC STANDARDS. ADDED SIDE VIEW DETAIL A. CORRECTED MARKING INFORMATION. REQ. BY D. TRUHITE.	29 JUN 2010
E	ADDED ALTERNATE CONSTRUCTION BOTTOM VIEW. MODIFIED DIMENSIONS b2 AND L1. CORRECTED MARKING DIAGRAM FOR DISCRETE. REQ. BY I. CAMBALIZA.	06 FEB 2014
F	ADDED SECOND ALTERNATE CONSTRUCTION BOTTOM VIEW. REQ. BY K. MUSTAFA.	21 JUL 2015

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